



# PBHV9560Z

600 V, 0.5 A PNP high-voltage low V<sub>CEsat</sub> (BISS) transistor

12 August 2014

Product data sheet

## 1. General description

PNP high-voltage low V<sub>CEsat</sub> Breakthrough In Small Signal (BISS) transistor in a medium power SOT223 (SC-73) Surface-Mounted Device (SMD) plastic package.

NPN complement: PBHV8560Z

## 2. Features and benefits

- High voltage
- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability I<sub>C</sub>
- High collector current gain h<sub>FE</sub> at high I<sub>C</sub>
- AEC-Q101 qualified

## 3. Applications

- Electronic ballast for fluorescent lighting
- LED driver for LED chain module
- LCD backlighting
- HID front lighting
- Automotive motor management
- Hook switch for wired telecom
- Switch Mode Power Supply (SMPS)

## 4. Quick reference data

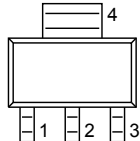
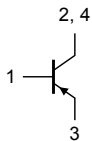
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-600	V
I <sub>C</sub>	collector current		-	-	-0.5	A
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -10 V; I <sub>C</sub> = -50 mA; T <sub>amb</sub> = 25 °C	70	130	-	



## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 <p><b>SC-73 (SOT223)</b></p>	 <p><i>sym028</i></p>
2	C	collector		
3	E	emitter		
4	C	collector		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBHV9560Z	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PBHV9560Z	HV956Z

## 8. Limiting values

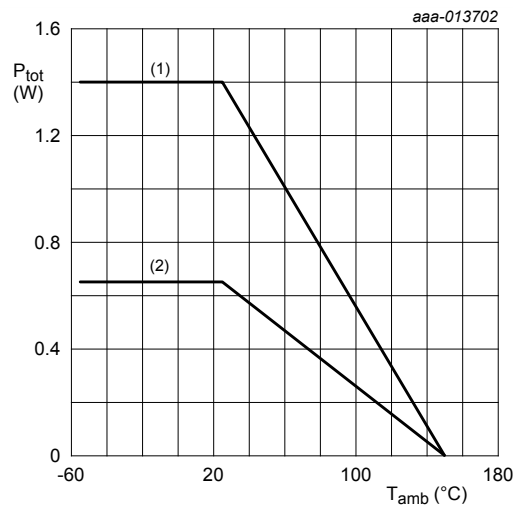
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter		-	-600	V
$V_{CEO}$	collector-emitter voltage	open base		-	-600	V
$V_{CESM}$	collector-emitter peak voltage	$V_{BE} = 0\text{ V}$		-	-600	V
$V_{EBO}$	emitter-base voltage	open collector		-	-6	V
$I_C$	collector current			-	-0.5	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^\circ\text{C}$	[1]	-	0.65	W
			[2]	-	1.4	W
$T_j$	junction temperature			-	150	$^\circ\text{C}$
$T_{amb}$	ambient temperature			-55	150	$^\circ\text{C}$
$T_{stg}$	storage temperature			-65	150	$^\circ\text{C}$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.



(1) FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>  
 (2) FR4 PCB, standard footprint

**Fig. 1. Power derating curves**

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	190	K/W
			[2]	-	-	89	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	20	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

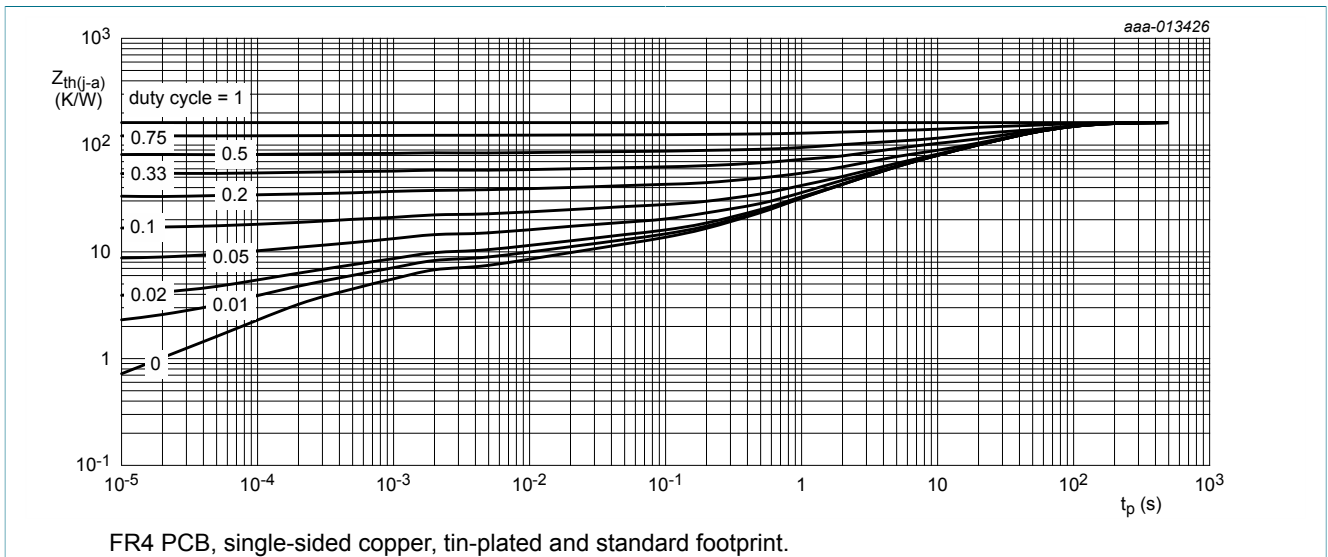


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

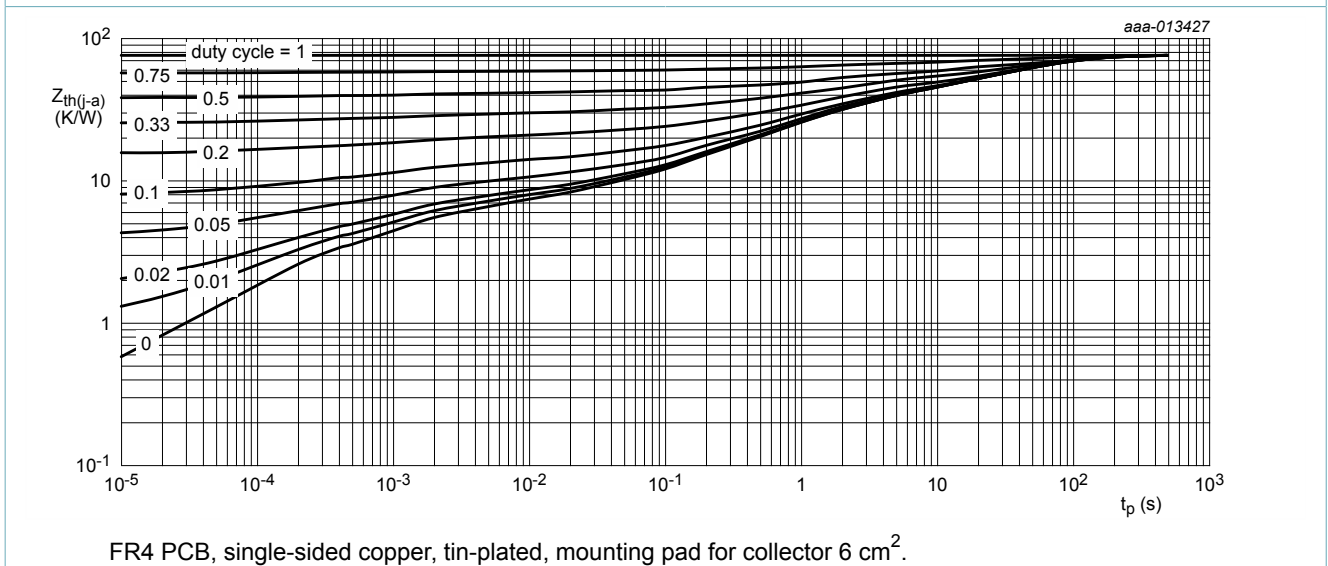
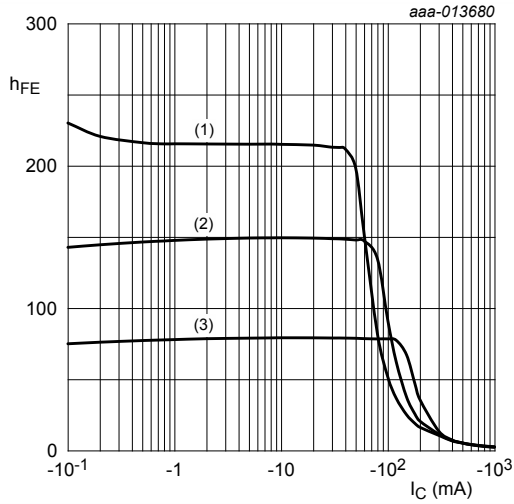


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

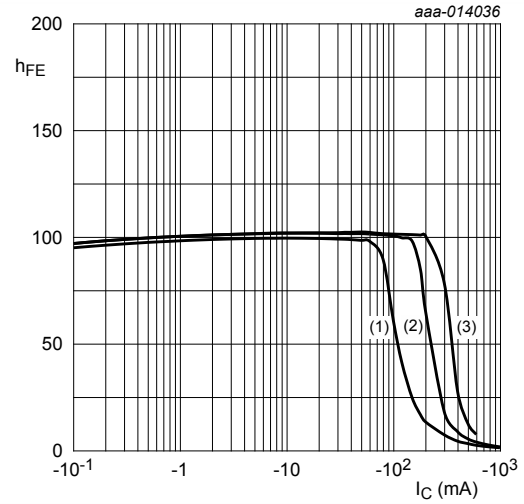
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -400 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
		V <sub>CB</sub> = -400 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	-10	μA
I <sub>CES</sub>	collector-emitter cut-off current	V <sub>CE</sub> = -400 V; V <sub>BE</sub> = 0 V; T <sub>amb</sub> = 25 °C	-	-	-100	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -10 V; I <sub>C</sub> = -50 mA; T <sub>amb</sub> = 25 °C	70	130	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -100 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	50	90	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -50 mA; I <sub>B</sub> = -5 mA; T <sub>amb</sub> = 25 °C	-	-150	-250	mV
		I <sub>C</sub> = -100 mA; I <sub>B</sub> = -20 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-140	-250	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = -50 mA; I <sub>B</sub> = -5 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	-900	mV
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = -10 V; I <sub>C</sub> = -30 mA; f = 100 MHz	-	38	-	MHz
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = -20 V; I <sub>E</sub> = 0 A; i <sub>e</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	12	-	pF
C <sub>e</sub>	emitter capacitance	V <sub>EB</sub> = -0.5 V; I <sub>C</sub> = 0 A; i <sub>c</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	390	-	pF



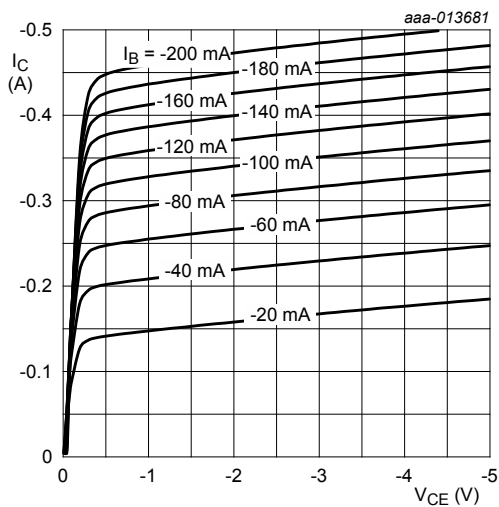
$V_{CE} = -10$  V  
 (1)  $T_{amb} = 100$  °C  
 (2)  $T_{amb} = 25$  °C  
 (3)  $T_{amb} = -55$  °C

**Fig. 4. DC current gain as a function of collector current; typical values**



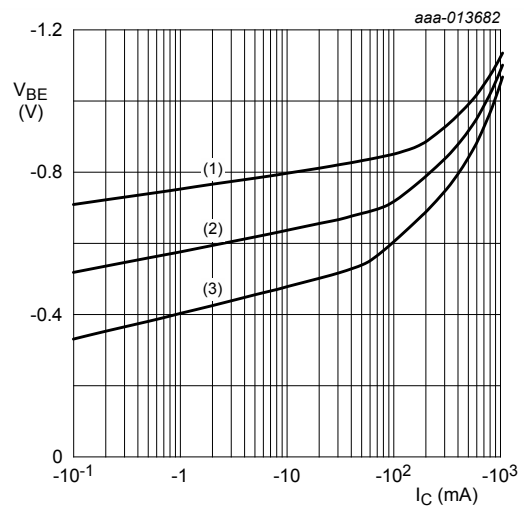
$h_{FE} = f(I_C)$   
 $T_{amb} = 25$  °C  
 (1)  $V_{CE} = -10$  V  
 (2)  $V_{CE} = -25$  V  
 (3)  $V_{CE} = -50$  V

**Fig. 5. DC current gain as a function of collector current; typical values**



$T_{amb} = 25$  °C

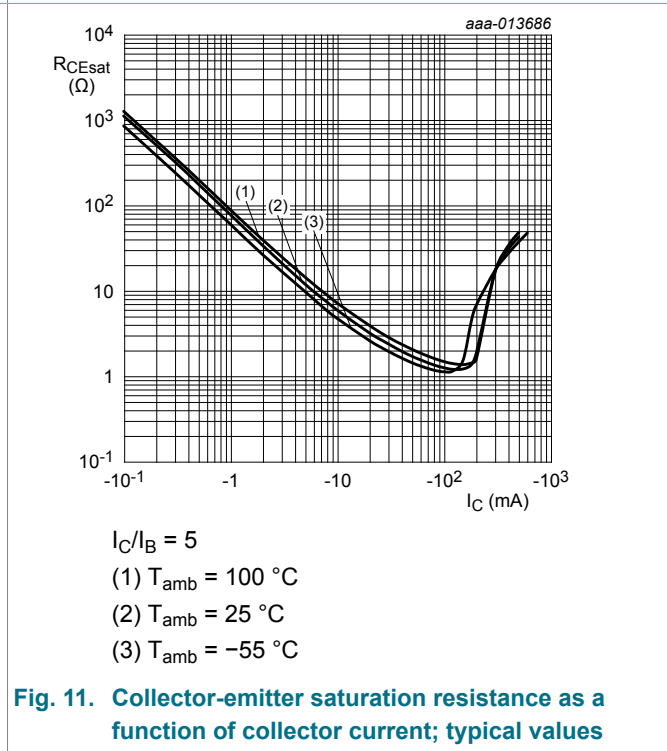
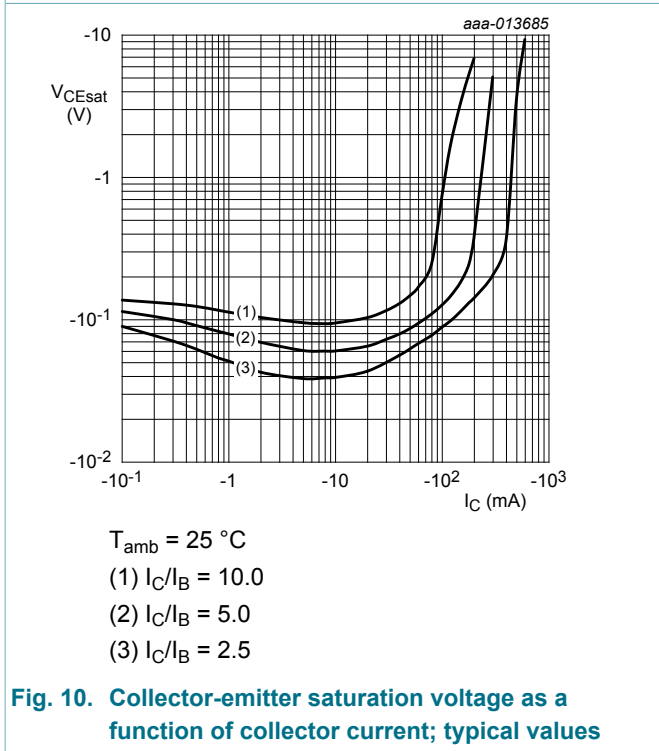
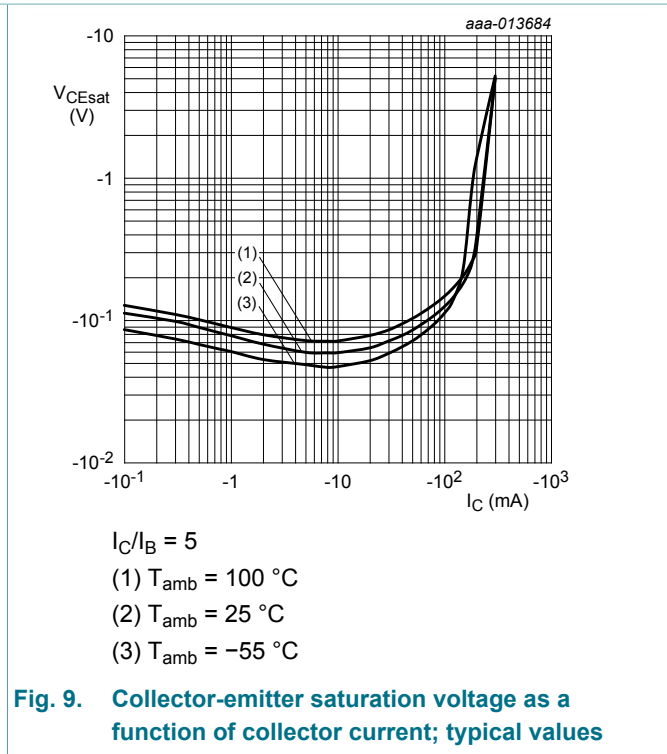
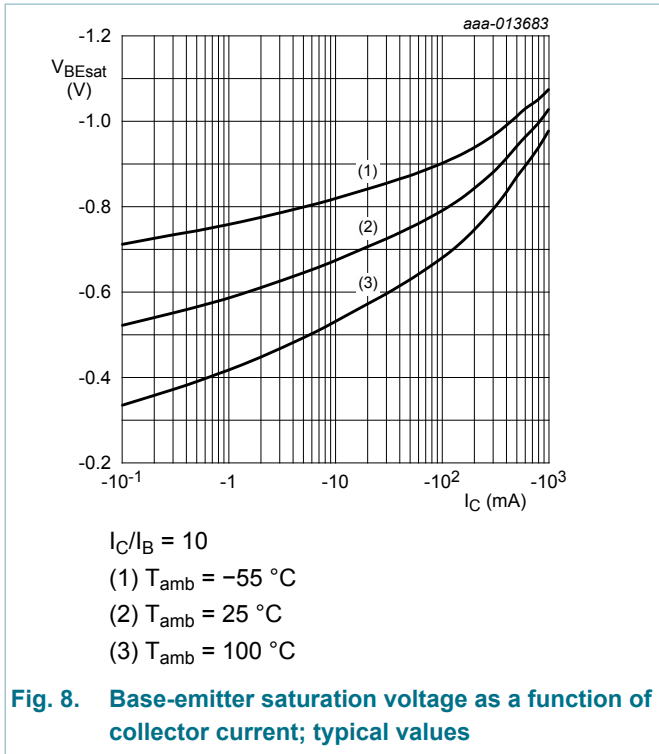
**Fig. 6. Collector current as a function of collector-emitter voltage; typical values**

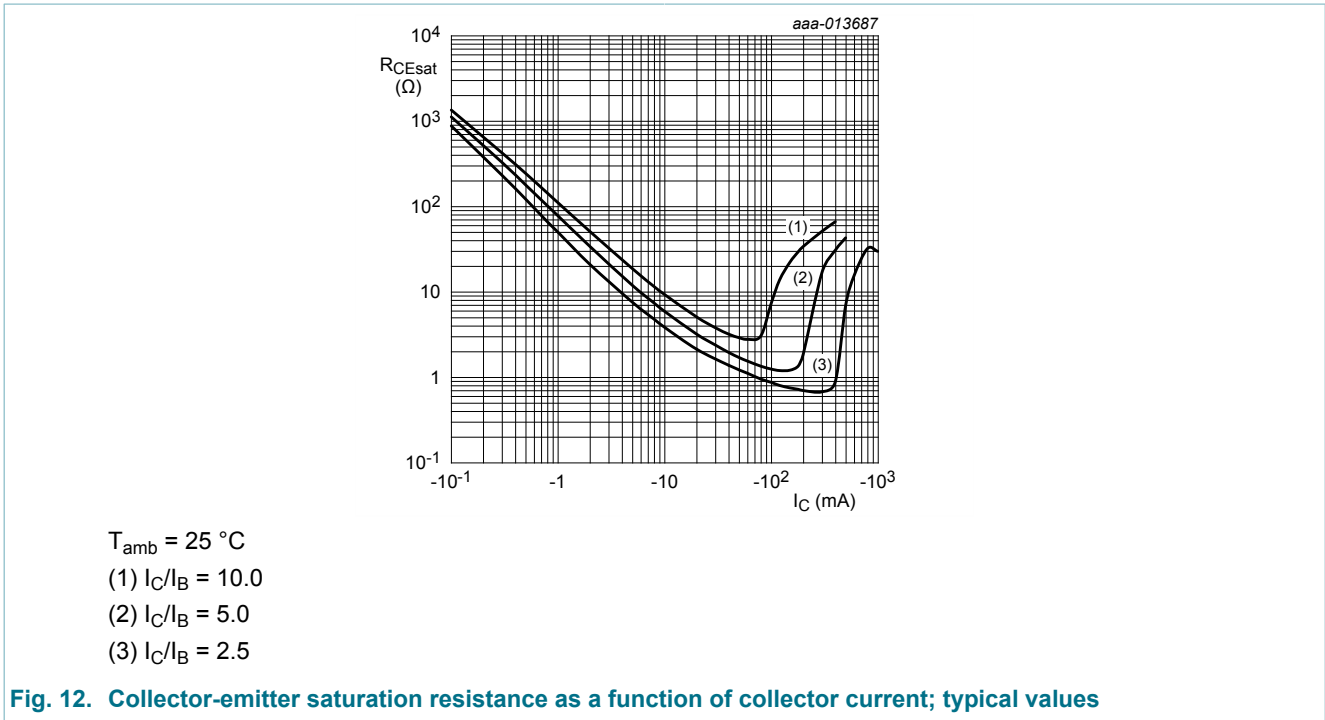


$V_{CE} = -5$  V  
 (1)  $T_{amb} = -55$  °C  
 (2)  $T_{amb} = 25$  °C  
 (3)  $T_{amb} = 100$  °C

**Fig. 7. Base-emitter voltage as a function of collector current; typical values**

600 V, 0.5 A PNP high-voltage low VCEsat (BISS) transistor





## 11. Test information

### 11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.



## 12. Package outline

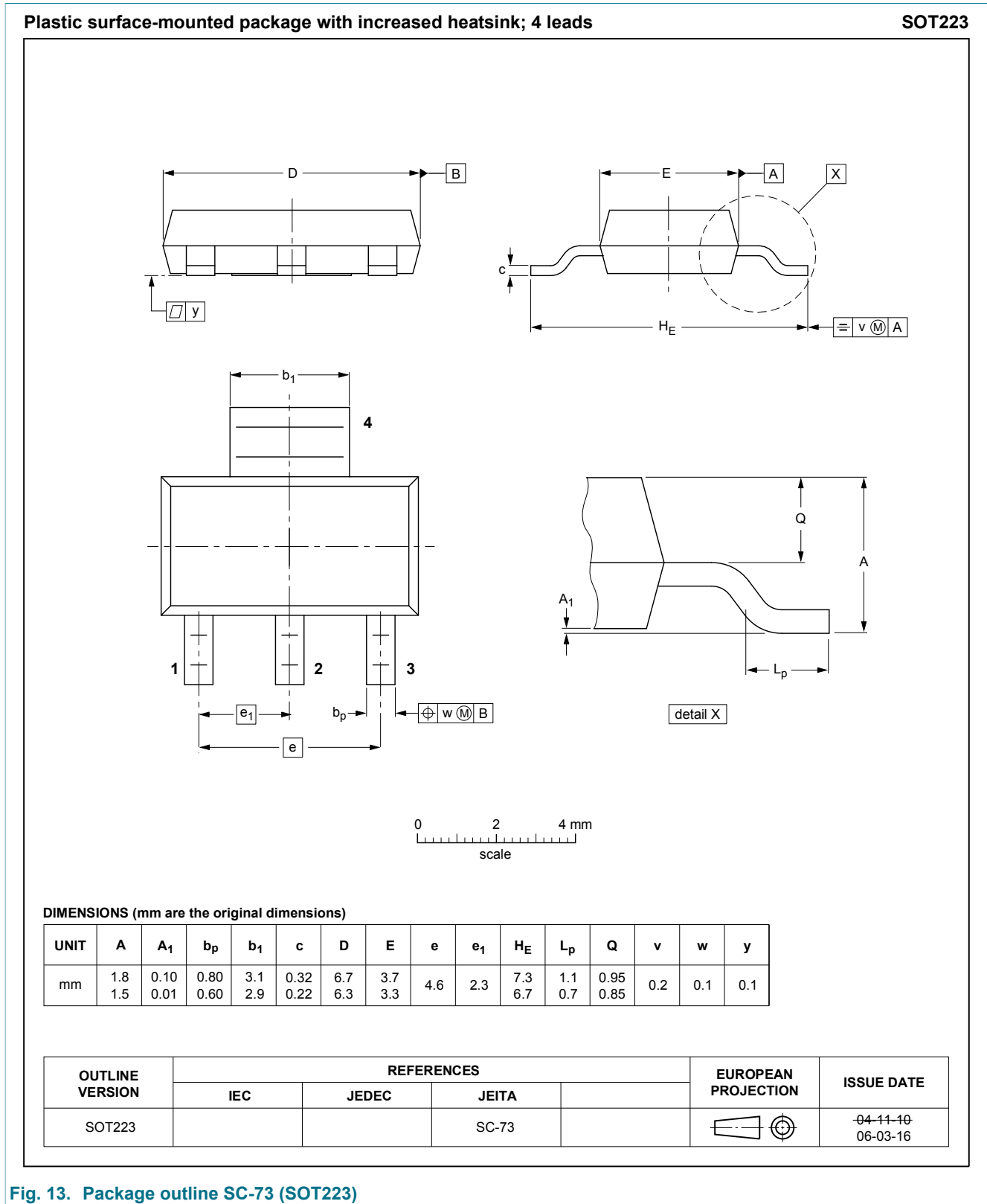


Fig. 13. Package outline SC-73 (SOT223)

### 13. Soldering

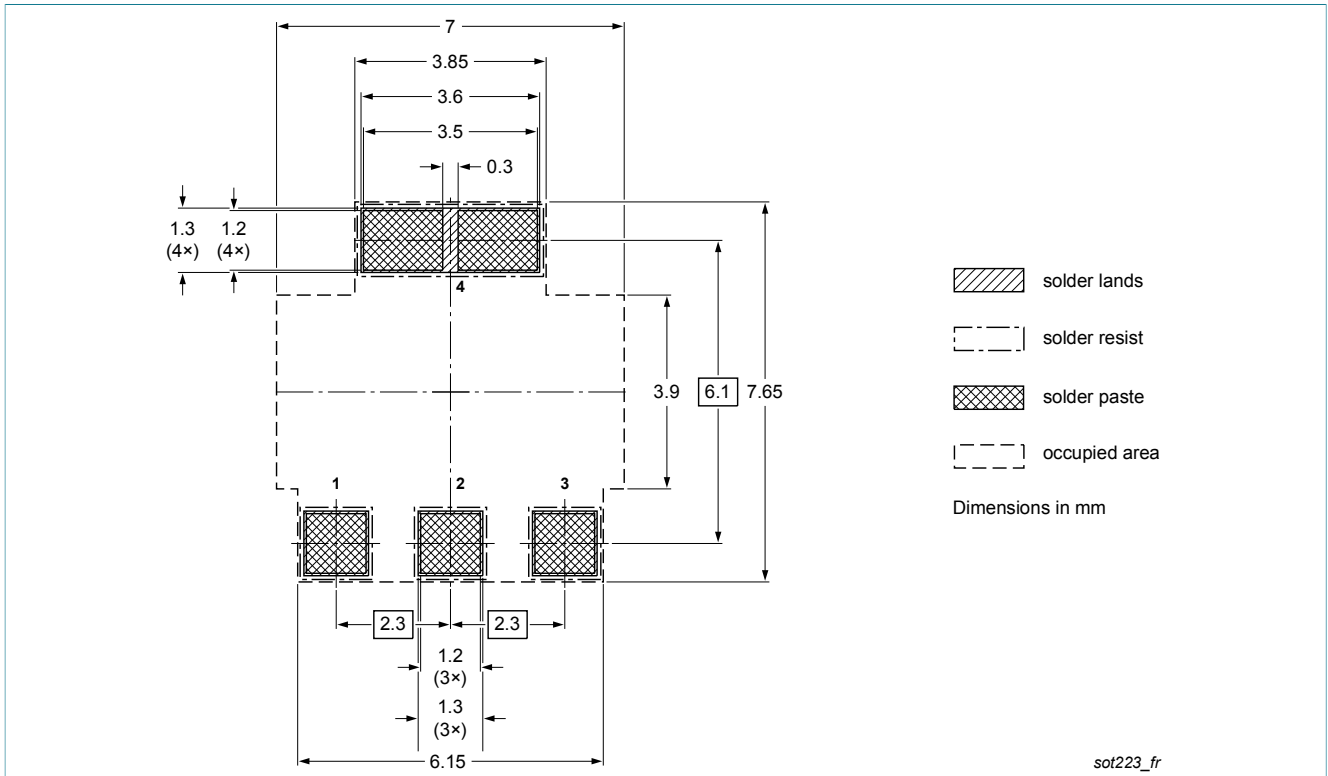


Fig. 14. Reflow soldering footprint for SC-73 (SOT223)

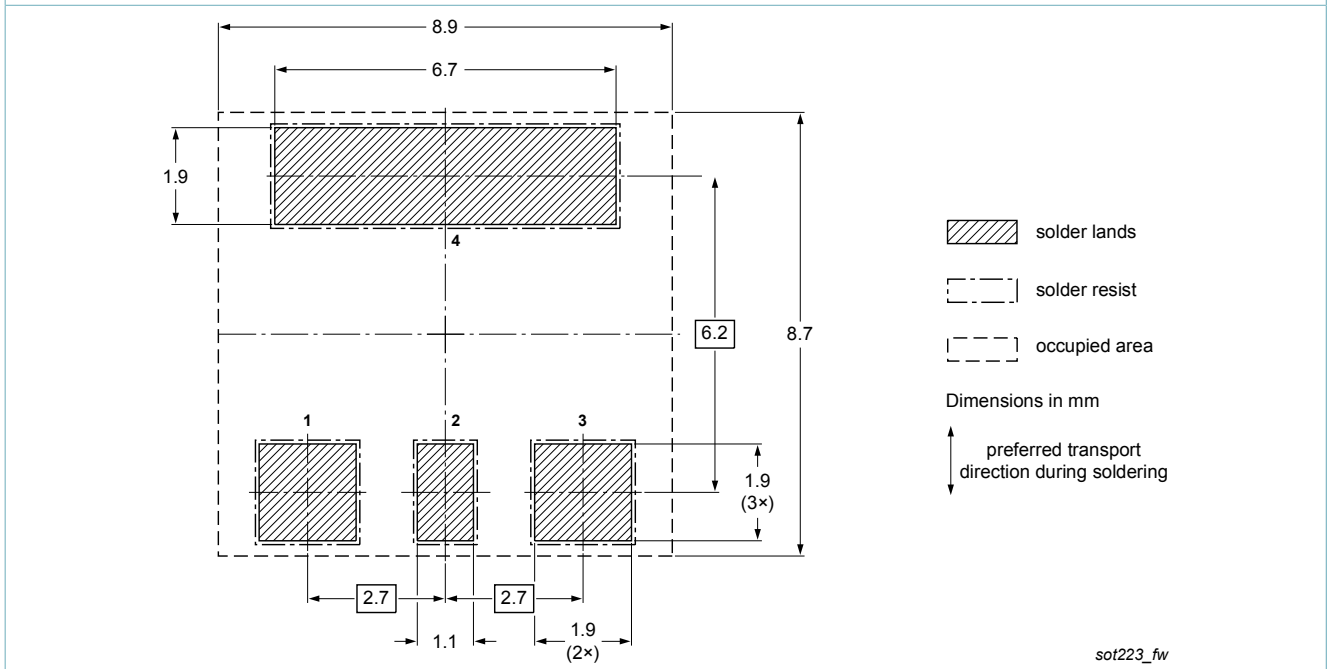


Fig. 15. Wave soldering footprint for SC-73 (SOT223)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBHV9560Z v.1	20140812	Product data sheet	-	-

## 15. Legal information

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Document status [1][2]	Product status [3]	Definition
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